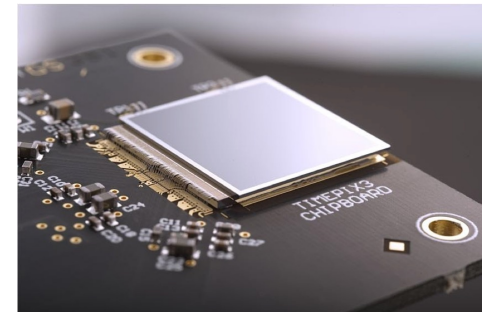


MEDIPIX4

S. Tudisco - M. Fiorini (Ferrara)

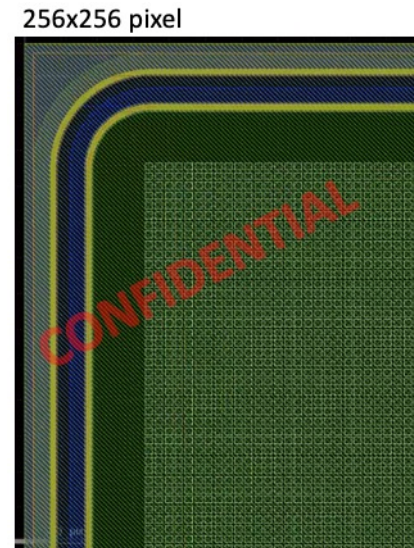
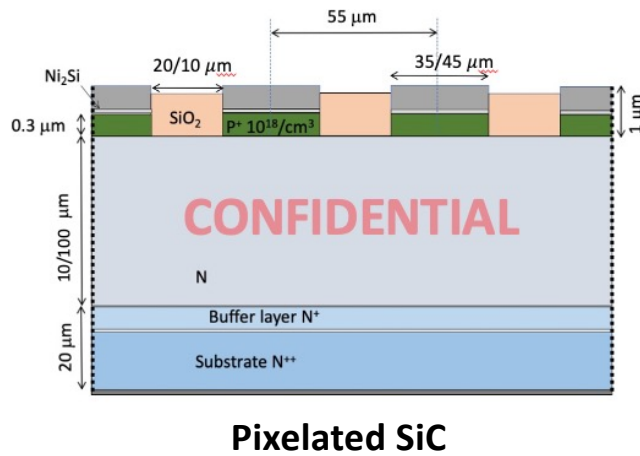
Main Goal

- **Acquire from Medipix4 CERN Collaboration** the new Timepix4 ASIC bump-bonded to different sensor technologies (Si, Cd-Zn-Te)
- **Test the new devices for Medical Applications**
- **Development of a new fast INFN-read-out**
- **Development of a new pixelated sensor based on Silicon Carbide**



Activity 2024

- New MEDIPIX characterization
- New devices Characterization (delay on prototype production)



Potenziale output scientifico

- New medical imaging device
- Possible Patent

Budget

- 4 k€ Missioni per misure TFPA e ELI
- 1 k€ Missioni assemblaggio SiC-TIMEPIX
- 4 k€ consumo: bump-bond dei dispositivi SiC su TIMEPIX
- 1 k€ consumo per set-up e misure

FTE

- S. Tudisco 0.1 FTE
- G. Lanzalone 0.2 FTE
- F. La Via 0.3 FTE
- S. De Luca 0.6 FTE
- G. Petringa 0.1 FTE

Impatto su divisioni e servizi LNS, eventuali necessità di spazi

- Elettronica e rivelatori (set-up di misura e caratterizzazione)
- Servizio sviluppo apparati (consulenza sul sistema di controllo)